
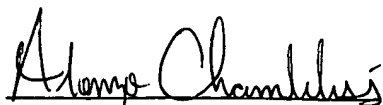


FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office				Attorney Docket Number 5308-390		Serial No. 10/815,293					
LIST OF DOCUMENTS CITED BY APPLICANT <div style="display: flex; align-items: center; justify-content: center;">  <div style="margin-left: 20px;"> (Use several sheets if necessary) </div> </div>								Applicant: Matthew Donofrio			
				Filing Date: April 1, 2004		Group: 2814					
U. S. PATENT DOCUMENTS											
Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate					
AC	1	6,504,180 B1	1/7/03	Heremans et al.	257	98					
I	2	6,483,196 B1	11/19/02	Wojnarowski et al.	257	778					
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AC	6	EP 1 263 058 A2	5/29/05	Europe	H01L	33/00					
AC	7	WO 2005/104253 A1	11/3/05	PCT	H01L	33/00					
AC	8	WO 02/073705 A2	9/19/02	PCT	H01L	33/00					
AC	9	WO 02/41362 A2	5/23/02	PCT	H01L						
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AC	12	Pan et al. "Improvement of InGaN-GaN Light-Emitting Diodes with Surface-Textured Indium-Tin-Oxide Transparent Ohmic Contacts," <i>IEEE Photonics Technology Letters</i> , Vol. 15, No. 5, May 2003.									
AC	13	Shafeev et al. "Uncongruent laser ablation and electroless metallization of SiC," <i>Applied Physics Letters</i> , Vol. 68, No. 6, February 5, 1996.									
AC	14	International Search Report and Written Opinion of the International Searching Authority for corresponding PCT application no. PCT/US2005/001933, issued 7/19/06.									

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Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.